TE Internal #: 2149730-4

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 16 Gb/s, Internal/External EMI Springs, SFP+ Enhanced, Not Optional, 1 x 4,

Through Hole - Press-Fit

View on TE.com >



Connectors > Pluggable IO Connectors & Cages > SFP, SFP+ & zSFP+



Pluggable I/O Product Type: Cage Assembly

Data Rate (Max): 16 Gb/s

EMI Containment Feature Type: Internal/External EMI Springs

Pluggable I/O Applications: SFP+ Enhanced

Lightpipe Options: Not Optional

Features

Product Type Features

Form Factor	SFP+
Cage Type	Ganged
Thermal Accessory Type Included	Heat Sink
Pluggable I/O Product Type	Cage Assembly
Lightpipe Options	Not Optional
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Port Matrix Configuration	1 x 4
Number of Ports	4

Electrical Characteristics

Data Rate (Max)	16 Gb/s

Body Features

Heat Sink Height Class	Networking Tall
Heat Sink Height	13.5 mm[.531 in]
Heat Sink Style	Pin

Termination Features



Termination Post & Tail Length	2.05 mm[.081 in]
Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Cage Material	Nickel Silver
Dimensions	
PCB Thickness (Recommended)	2.25 mm[.089 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Heat Sink Compatible	Yes
For Use With Pluggable I/O Products	SFP+ SMT Connector
Pluggable I/O Applications	SFP+ Enhanced
Circuit Application	Signal
Packaging Features	
Packaging Method	Box & Tray, Package
Other	

Product Compliance

EMI Containment Feature Type

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not applicable for solder process capability

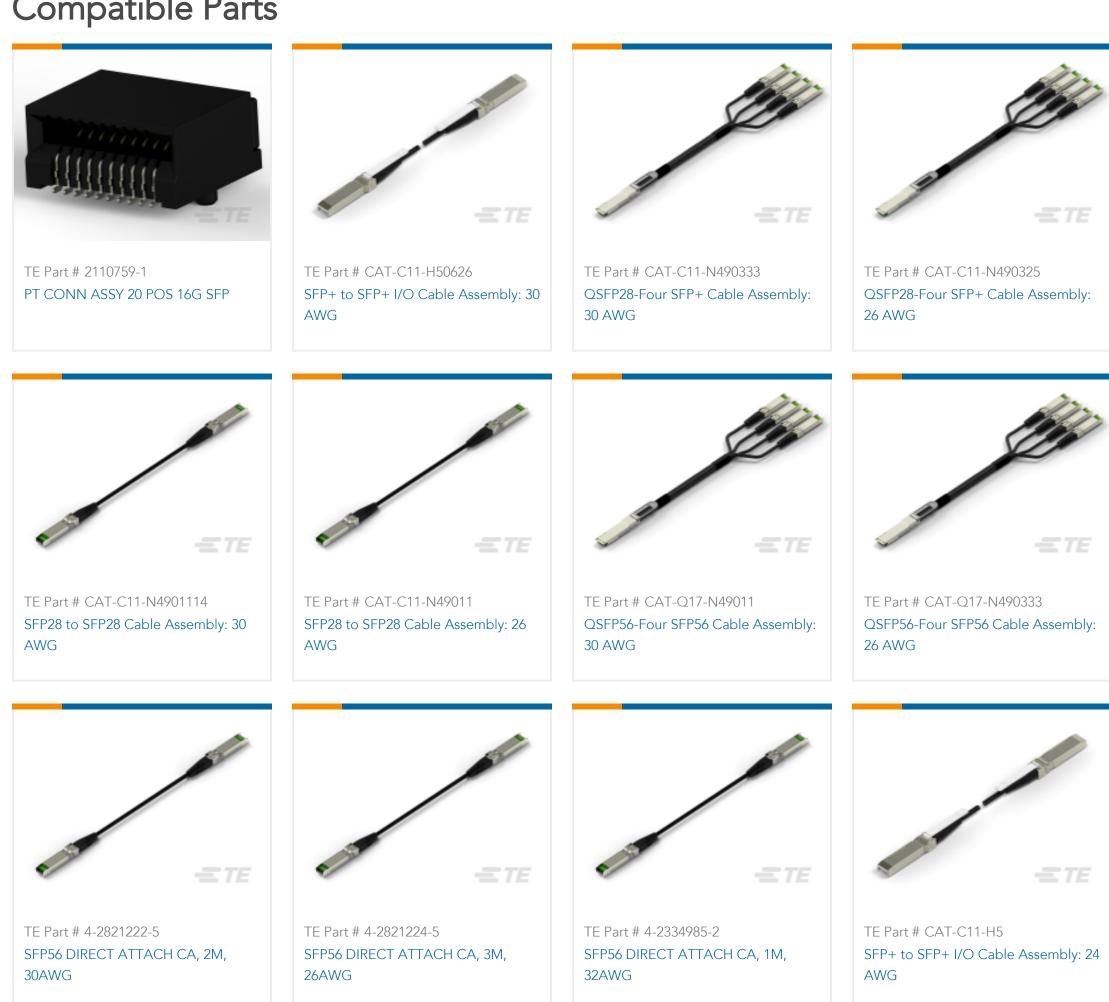
Internal/External EMI Springs



Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts





















Customers Also Bought













Documents

CAD Files

3D PDF

3D

Customer View Model ENG_CVM_CVM_2149730-4_A.2d_dxf.zip

English

Customer View Model ENG_CVM_CVM_2149730-4_A.3d_igs.zip

English



Customer View Model

ENG_CVM_CVM_2149730-4_A.3d_stp.zip

English

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Product Specifications

Application Specification

English

Product Environmental Compliance

TE Material Declaration

English